

**AMENDMENTS TO THE CLAIMS**

**Please amend the claims as follows:**

1. (Currently Amended)      A radiographic apparatus comprising:
  - a substrate;
  - a conversion portion having a plurality of ~~first semiconductor conversion devices that are arranged on said substrate in a matrix to convert radiation into an electrical signal, and switching devices that are connected to each of said plurality of first semiconductor conversion devices~~ pixels arranged on said substrate in a matrix, each pixel including a first semiconductor conversion device which converts radiation into an electrical signal and a switching device which is connected to said first semiconductor conversion device;
  - a plurality of second semiconductor conversion devices arranged on said substrate to convert radiation into an electrical signal to detect ~~irradiation~~ the amount of radiation incident on said conversion portion; and
  - ~~wiring lines connected to each of said plurality of first semiconductor conversion devices, and connected to a plurality of printed wiring boards~~ which are respectively connected to said plurality of pixels,
  - wherein said conversion portion includes a plurality of pixel regions each having at least one pixel; each of said plurality of pixel regions corresponding to respective one of said plurality of printed writing boards;
  - said plurality of second semiconductor conversion devices are ~~collectively arranged in a region where said first semiconductor conversion devices which are connected to at least one specific printed wiring board selected from the plurality of printed wiring boards are collectively arranged~~ arranged in one or some of said plurality of pixel regions, and said second semiconductor conversion devices and

said pixels arranged in the same pixel region are connected to the same printed writing board.

2. (Currently Amended)      The apparatus according to claim 1, wherein  
control wiring lines for controlling an operation of said switching devices  
and signal lines for transmitting signals output from said first semiconductor  
conversion devices through said switching devices are arranged in said conversion  
portion ~~to be perpendicular to each other, and~~  
the specific said printed wiring board to which said second semiconductor  
conversion devices are connected is connected to a printed wiring board to which  
the signal lines are connected.

3. (Currently Amended)      The apparatus according to claim 2, wherein ~~the~~  
~~printed wiring boards to which the signal lines are connected are arranged in~~  
~~equal numbers on two opposing sides of said substrate while sandwiching said~~  
~~conversion portion~~ said first semiconductor conversion device includes a first  
group of a first size semiconductor conversion devices and a second group of a  
second size semiconductor conversion devices; said second size being smaller  
than said first size, wherein said second group of said second size semiconductor  
conversion devices is arranged adjacent to said second semiconductor conversion  
devices.

4. (Currently Amended)      The apparatus according to claim 3, wherein when  
said first semiconductor conversion devices are divided into two groups including  
the same numbers of first semiconductor conversion devices by a boundary line  
parallel to ~~the two sides~~ two opposing sides of said substrate, said second

semiconductor conversion devices are arranged in line symmetry about the boundary line serving as an axis of symmetry.

5. (Currently Amended) The apparatus according to claim 1, wherein  
~~control wiring lines for controlling an operation of said switching devices~~  
~~and signal lines for transmitting signals output from said first semiconductor~~  
~~conversion devices through said switching devices are arranged in said conversion~~  
~~portion to be perpendicular to each other, and~~  
~~the specific printed wiring board is a printed wiring board to which the~~  
~~control wiring lines are connected~~  
said printing writing board has a semiconductor chip thereon, and said  
plurality of pixels are connected to said semiconductor chip and said second  
semiconductor conversion devices are not connected to said semiconductor chip.

6. (Currently Amended) The apparatus according to claim 5, wherein the  
~~printed wiring boards to which the control wiring lines are connected are arranged~~  
~~in equal numbers on two opposing sides of said substrate while sandwiching said~~  
~~conversion portion~~ said printed writing board has a spare wiring line which is not  
connected to said semiconductor chip and said plurality of second semiconductor  
conversion devices are connected to said spare wiring line.

7. (Currently Amended) The apparatus according to claim 6, ~~wherein when~~  
~~said first semiconductor conversion devices are divided into two groups including~~  
~~the same numbers of first semiconductor conversion devices by a boundary line~~  
~~parallel to the two sides, said second semiconductor conversion devices are~~  
~~arranged in line symmetry about the boundary line serving as an axis of symmetry~~

5, further comprising a read circuit which is connected to said semiconductor chip, and a circuit which is separated from said semiconductor chip and connected to said spare wiring line to detect the amount of radiation.

8. (Original) A radiographic system comprising:

a radiation source for generating radiation;

a radiation detection apparatus of claim 1 for converting the radiation incident from said radiation source into an electrical signal;

an image processor for image-processing the electrical signal output from said radiation detection apparatus; and

a display for displaying the electrical signal image-processed by said image processor.

9. (Original) The system according to claim 8, wherein

the system further comprises a transmission processing unit arranged to transmit the electrical signal output from said image processor, and

said image processor outputs the signal to said display through said transmission processing unit.